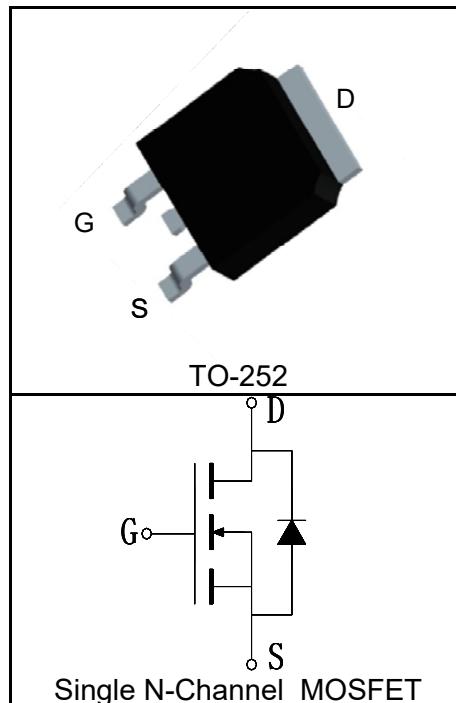


## Features

- 60V/80A,
- $R_{DS\ (ON)} = 7m\Omega$ (Typ.)@ $V_{GS}=10V$
- Low  $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

## Pin Description



## Applications

- Power Switching Application
- Load Switching



Halogen-Free

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_C=25^\circ C$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$T_J$	Maximum Junction Temperature	175	°C
$T_{STG}$	Storage Temperature Range	-55 to 175	°C
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$	A
<b>Mounted on Large Heat Sink</b>			
$I_{DP}^{(1)}$	300μs Pulse Drain Current Tested	$T_C=25^\circ C$	320
$I_D^{(2)}$	Continuous Drain Current( $V_{GS}=10V$ )	$T_C=25^\circ C$	80
		$T_C=100^\circ C$	56
$P_D$	Maximum Power Dissipation	$T_C=25^\circ C$	100
		$T_C=100^\circ C$	50
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.5	°C/W
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	100	°C/W
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	324	mJ

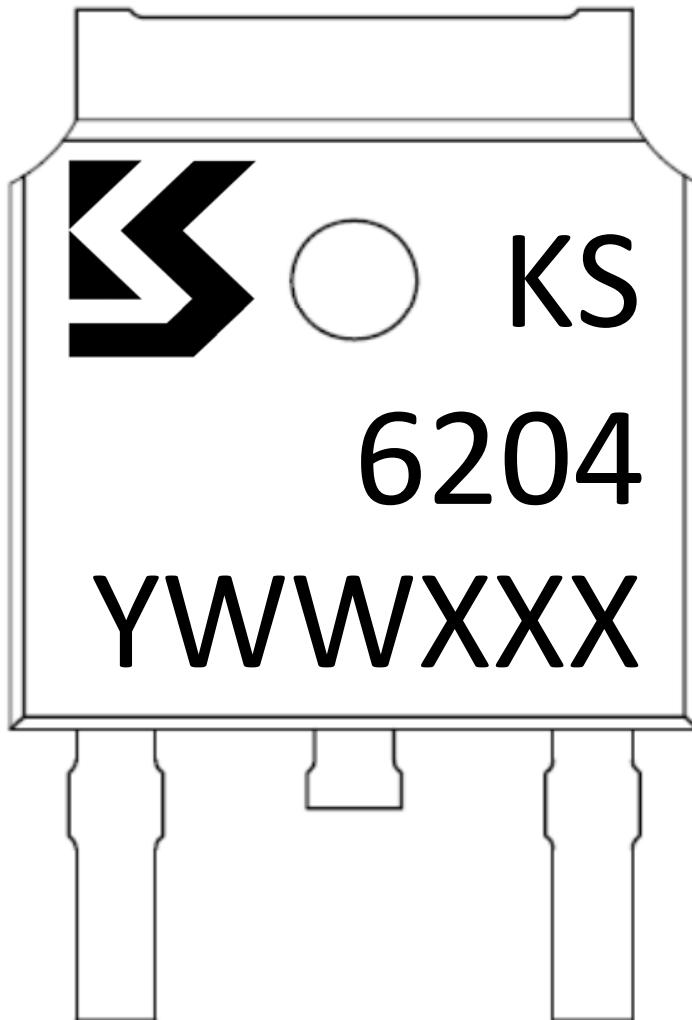
**Electrical Characteristics (T<sub>C</sub>=25°C Unless Otherwise Noted)**

Symbol	Parameter	Test Condition	KS6204DB			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1	μA
		T <sub>J</sub> =125°C			30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	2	3	4	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V			±100	nA
R <sub>DS(ON)</sub> <sup>⑤</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		7	9	mΩ
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>⑤</sup>	Diode Forward Voltage	I <sub>SD</sub> =40A, V <sub>GS</sub> =0V		0.87	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =40A, dI <sub>SD</sub> /dt=100A/μs		45		ns
Q <sub>rr</sub>	Reverse Recovery Charge			90		nC
<b>Dynamic Characteristics<sup>⑥</sup></b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		1.4		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, Frequency=1.0MHz		2850		pF
C <sub>oss</sub>	Output Capacitance			335		
C <sub>rss</sub>	Reverse Transfer Capacitance			190		
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>DS</sub> =40A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω		13		ns
t <sub>r</sub>	Turn-on Rise Time			25		
t <sub>d(OFF)</sub>	Turn-off Delay Time			49		
t <sub>f</sub>	Turn-off Fall Time			21		
<b>Gate Charge Characteristics<sup>⑥</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =48V, V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		54		nC
Q <sub>gs</sub>	Gate-Source Charge			10		
Q <sub>gd</sub>	Gate-Drain Charge			17		

- Notes:
- ①Pulse width limited by safe operating area.
  - ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 60A.
  - ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
  - ④Limited by T<sub>Jmax</sub>, I<sub>AS</sub> =36A, L=0.5mH, V<sub>DD</sub> = 48V, R<sub>G</sub> = 25Ω , Starting TJ = 25°C.
  - ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
  - ⑥Guaranteed by design, not subject to production testing.

**Ordering and Marking Information**

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS6204DB	TO-252	Tape&Reel	2500	13"	16mm

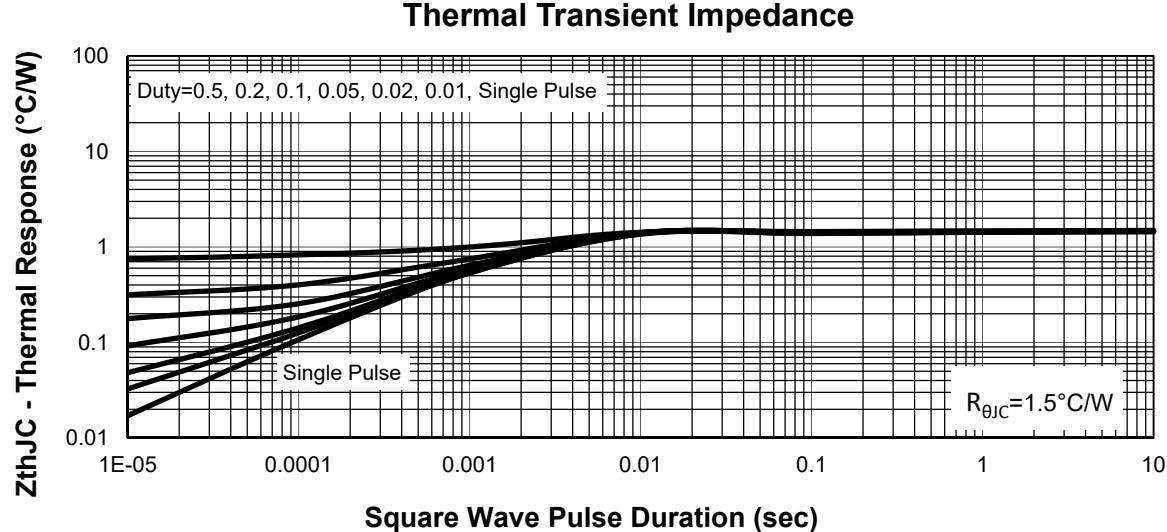
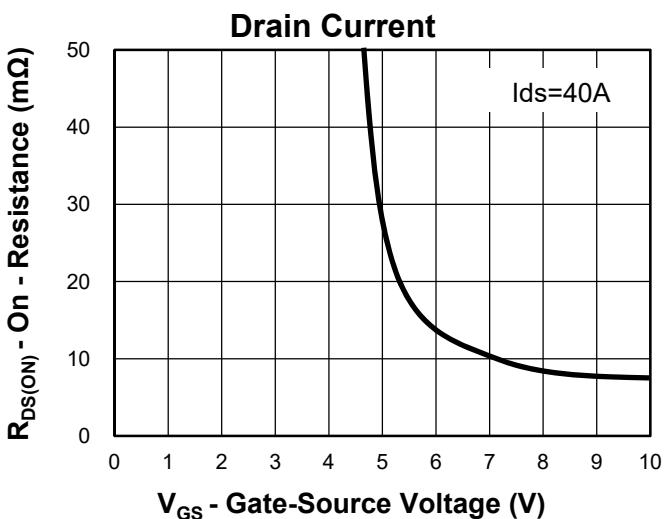
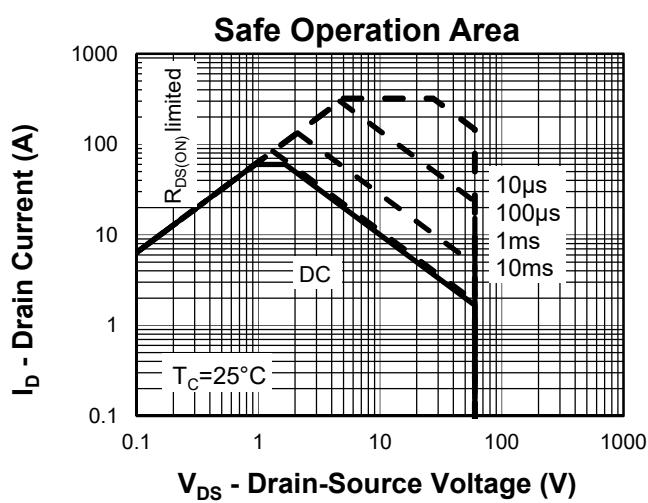
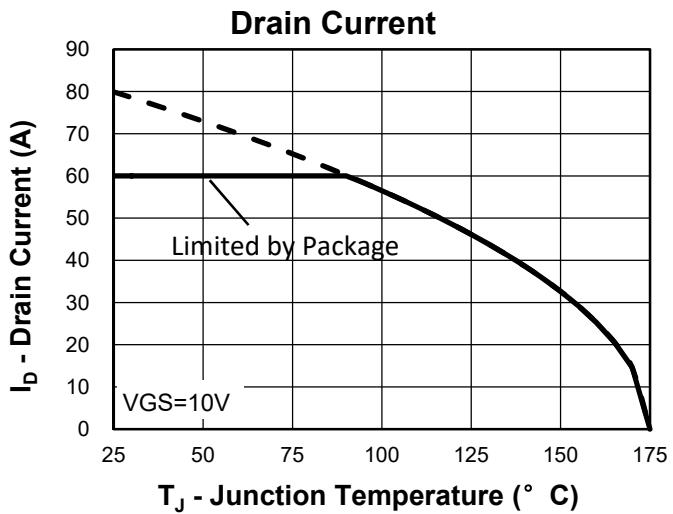
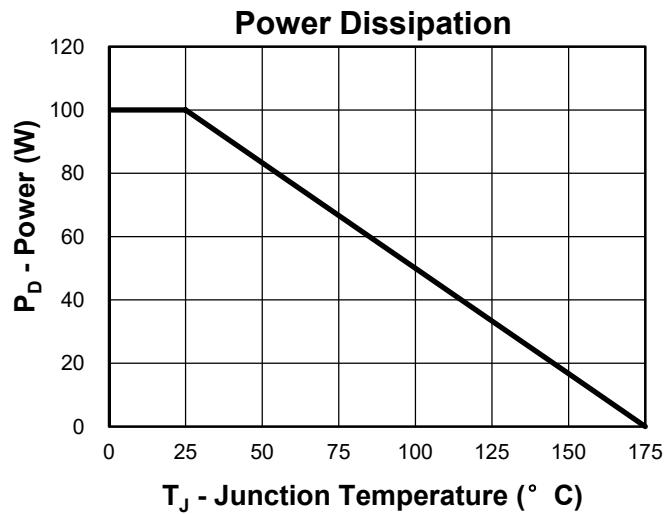


Y =Year, 2017-A, 2018-B,etc.

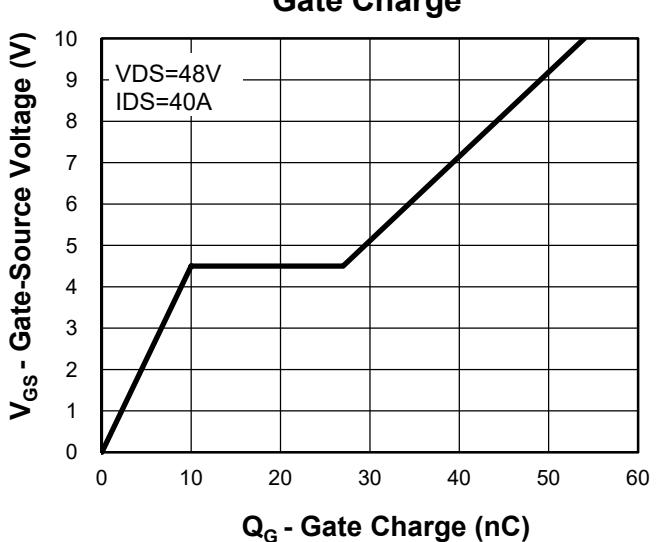
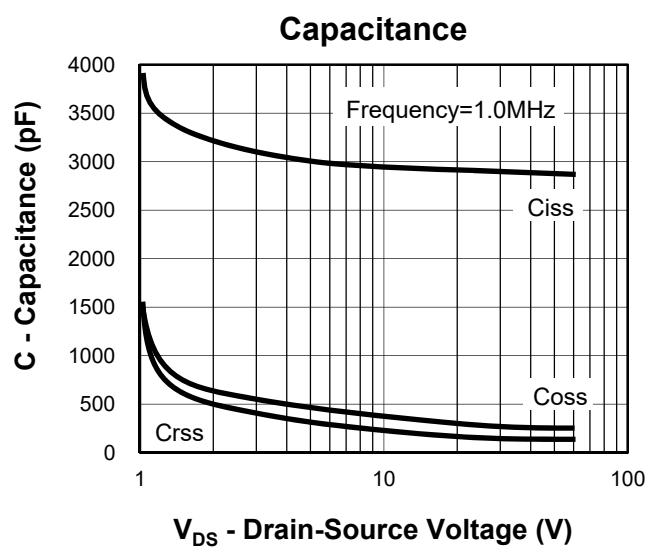
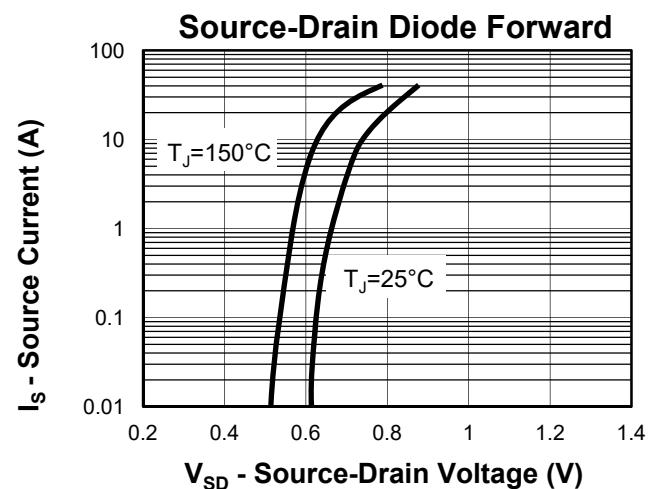
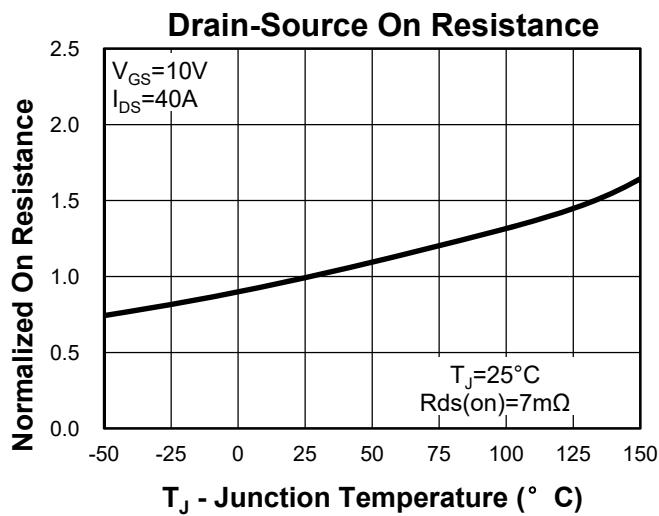
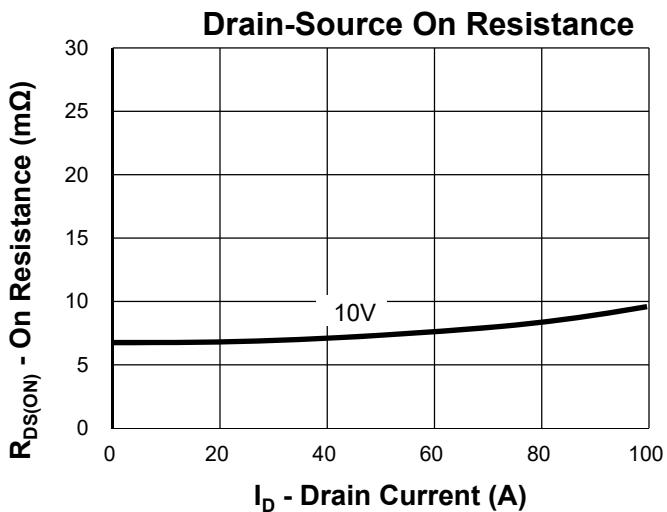
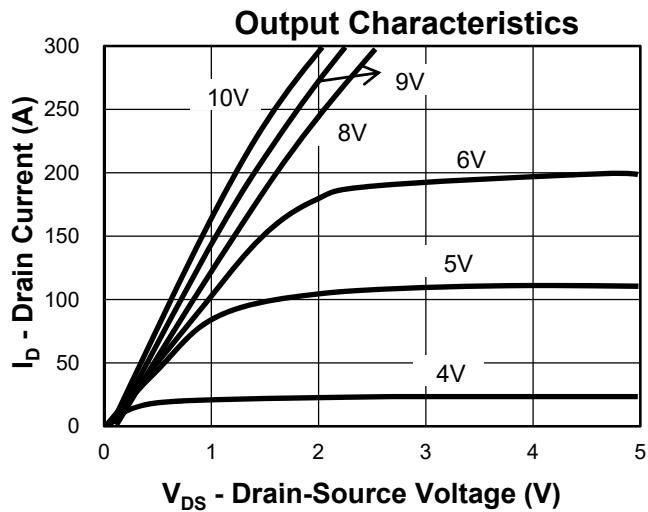
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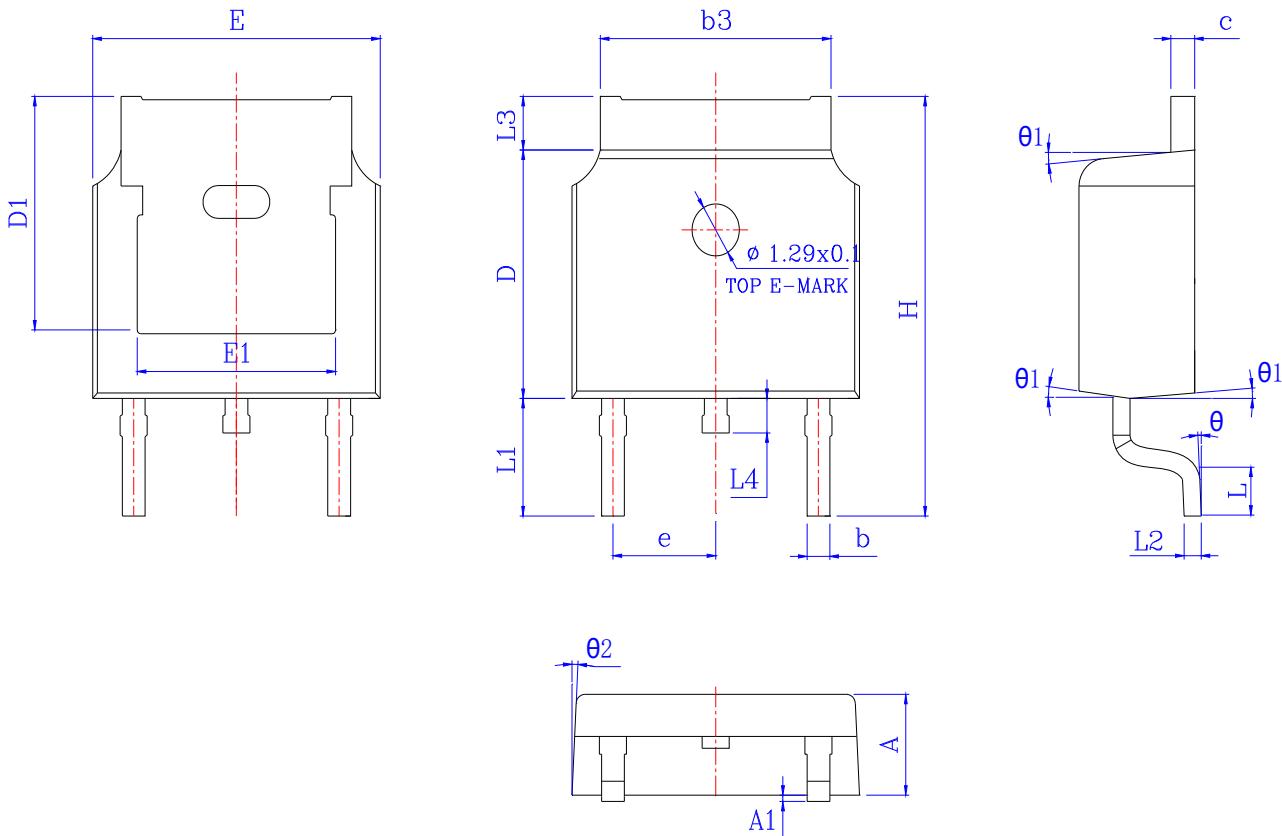
XXX =Lot number.

## Typical Characteristics



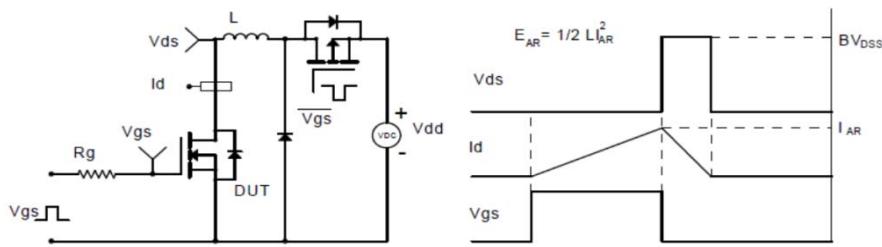
## Typical Characteristics



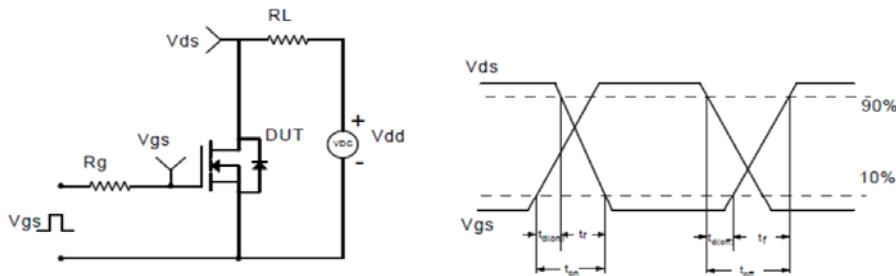
**Package Information**
**TO-252**


SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.200	2.300	2.400	0.087	0.091	0.094
A1	*	*	0.100	*	*	0.004
b	0.660	0.760	0.860	0.026	0.030	0.034
b3	5.130	5.295	5.460	0.202	0.208	0.215
c	0.470	0.535	0.600	0.019	0.021	0.024
D	6.000	6.100	6.200	0.236	0.240	0.244
D1	5.30 REF			0.20 REF		
E	6.500	6.600	6.700	0.256	0.260	0.264
E1	4.700	4.810	4.920	0.185	0.189	0.194
e	2.28 REF			0.09 REF		
H	9.800	10.100	10.400	0.386	0.398	0.409
L	1.400	1.550	1.700	0.055	0.061	0.067
L1	2.743 REF			0.108 REF		
L2	0.510 BSC			0.020 BSC		
L3	0.900	1.075	1.250	0.035	0.042	0.049
L4	0.600	0.800	1.000	0.024	0.031	0.039
θ	0°	*	8°	0°	*	8°
θ1	5°	7°	9°	5°	7°	9°
θ2	5°	7°	9°	5°	7°	9°

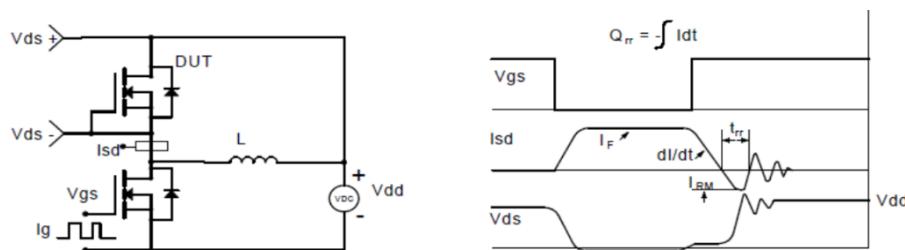
### Avalanche Test Circuit and Waveforms



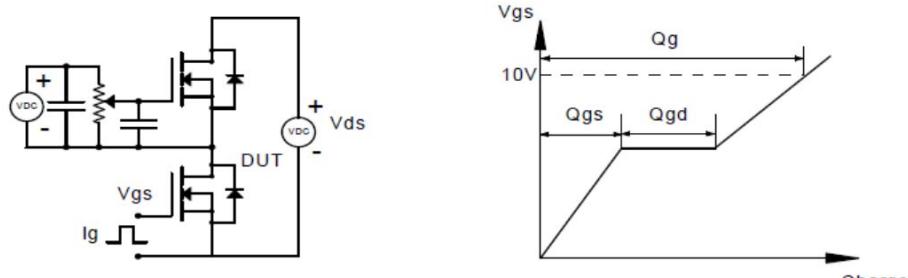
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



### Customer Service

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Web:[www.kwansemi.com](http://www.kwansemi.com)

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